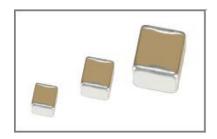


# ■ High Q MLCC (HQ SERIES)



#### **♦**Feature

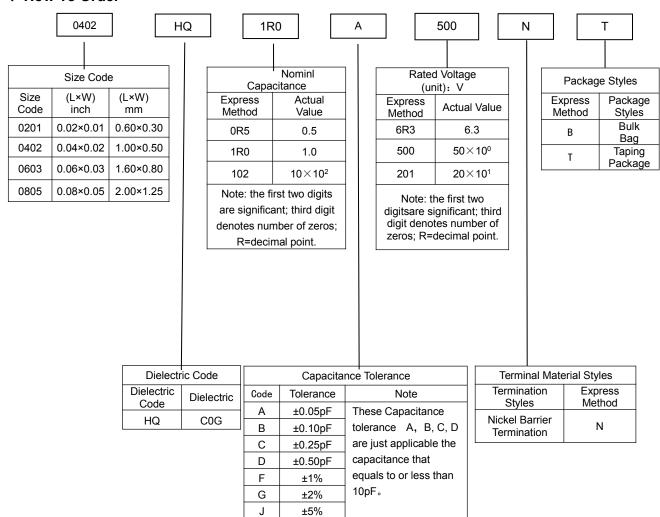
- \* There is high reliability on monolithic structure of laminated layers.
- \* And its character of excellent soldering ability and soldering resistance ability is suitable for reflow soldering and peak soldering.
  - \*It includes high and stable capacitance.
  - \* Internal electrodes use copper metal paste
  - \* High Q
  - \* Low equivalent series resistance
  - \* Executive Standard: GB/T 21041-2007

## **◆**Application

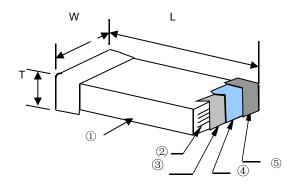
- \* Communication devices
- \* RF power amplifier
- \* Filter network



#### **♦** How To Order



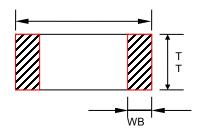
#### **♦ Product Structure**

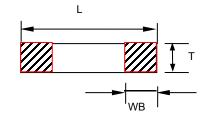


NO	Name
1)	Ceramic dielectric
2	Inner electrode (Cu)
3	Substrate electrode
4	Nickel Layer
5	Tin Layer



# ♦ Product Dimensions





Ту	ре	Dimensions (mm)					
British expression	Metric expression	L	W	Т	WB		
0201	0603	0.60±0.03	0.30±0.03	0.30±0.03	0.15±0.05		
0402	1005	1.00±0.05	0.50±0.05	0.50±0.05	0.25±0.05		
0603	1608	1.60±0.10	0.80±0.10	0.80±0.10	0.35±0.20		
0805	2012	2.00±0.20	1.25±0.20	0.80±0.20	0.50±0.20		

Note: We can design according to customer special requirements

## **♦** Temperature Coefficient /Characteristics

Dielectric	Reference Temperature Point	Temperature Coefficient	Operation Temperature Range
C0G	20°C	0±30ppm/°C	-55℃~125℃

## **◆** Capacitance Range and Operating Voltage

Dielectric		C0G											
Dimension	0201		0402			0603				0805			
Voltage	25V	50V	25V	50V	25V	50V	100V	200/ 250V	25V	50V	100V	200/250V	
Capacitance													
0.1pF													
0.2pF													
0.3pF													
0.4pF													
0.5pF													
0.6 pF													
0.7pF													
1.0pF													
1.2pF													
1.5pF													
1.8pF													
2.0pF													
2.2pF													
3.3pF													
3.9pF													
4.7pF													
5.6pF													

Note: 1、 Normal production 2、 We can design according to the customer requirements.



Dielectric		COG										
Dimension	02	01	04	0402			0603				0805	
Voltage	25V	50V	25V	50V	25V	50V	100V	200/ 250V	25V	50V	100V	200/250V
Capacitance												
6.8pF												
8.2pF												
10pF												
12pF												
15pF												
18pF												
22pF												
27pF												
33pF												
39pF												
47pF												
56pF												
68pF												
82pF												
100pF												
120pF												
150pF												
180pF												
220pF												
270pF												
330pF												
390pF												
470pF												
560pF												
680pF												
820pF												
1000pF												
1200pF												
1500pF												

Note: 1、 Normal production 2、 We can design according to the customer requirements.

## **♦**Reliability Test

Item	Technical Specification	Test Method and Remarks					
		Capacitance	Measuring Frequency	Measuring Voltage			
Capacitance	Should be within the specified tolerance.	≤1000pF	1MHz±10%	4.0.0.01/			
		>1000 pF	1KHz±10%	1.0±0.2Vrms			
Q	C≥30pF, Q≥1000 C<30pF, Q≥400+20C	Test Frequency: 1MHz±10% Test Voltage: 1.0±0.2Vrms					



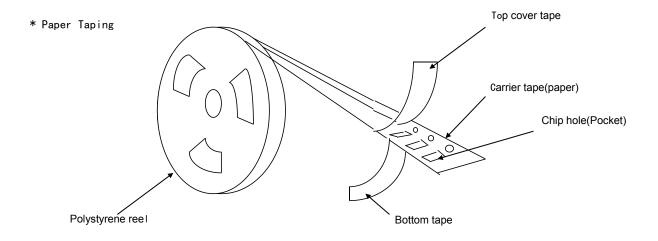
Item		Technical Specificat	ion	Test Method a	nd Remarks		
(IR) Insulation Resistance	≥10,000M	ΙΩ		Measuring Voltage: Rated Voltage (Max 500V) Duration: 60±5s Test Humidity: ≤75% Test Temperature: 25℃±3℃ Test Current: ≤50mA			
Dielectric Withstanding Voltage	No breakd	own or damage.		Measuring Voltage: Class I :300% Rated voltage Duration: 1~5s Charge/ Discharge Current: 50mA max.			
	A4 I4 O5	:0/ -5 N 4	- d- id b	Preheating conditions:80 to 120	℃; 10~30s.		
Solderability	new solder	6% of the terminal electron.  earance: No visible dam	•	Pb-Sn soldering Solder Temperature: 235±5℃ Duration: 2±0.5s	Lead-free soldering SolderTemperature:245±℃ Duration: 2±0.5s		
	ΔC/C	$\leq$ $\pm$ 2.5% or $\pm$ 0.25 larger	PF, whichever is	Preheating conditions: 100 to 20	00°C; 60−120s.		
Resistance to Soldering	Q	Same to initial value.		Solder Temperature: 265±5℃  Duration: 10±1s  Clean the capacitor with solv	vent and examine it with a		
Heat	IR	Same to initial value.		10X(min.) microscope. Recovery Time: 24±2h			
		ce: No visible damage.A ectrode is covered by ne		Recovery condition: Room temp	perature		
Resistance to Flexure of Substrate	Appearanc	ce: No visible damage.		Test Board: PCB Warp: 1m Speed: 1mm/sec. UThe measurement should be bending position.	nit: mm		
(Bending Strength)	ΔC/C	Within ±5% or ±0.5p larger	F, whichever is	1mm 45±2 45±2			
Termination Adhesion	No visible	damage.	of the capacitor a	picture , Slowly apply a T force to and hold for 60+1 seconds.  Apply orce T  2N  5N	the porcelain body on the side  T  R  R  PCB 时  国定共		



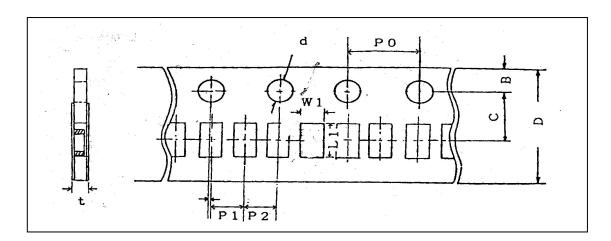
em  C/C ≤	±1% or ±1pF, whichever is larger	Step 1 2 3	Measurement g Times: 5 times, 1 cycle, 4 steps:  (Temperature) (°C)  (Low- category temp.):  (C0G:-55)  (Normal temp.): +20°C  (Up- category temp.)  (C0G: +125)  (Normal temp.): +20°C  ery time after test: 24±2h	(Time) 30min 2~3min 30min 2~3min			
. C/C ≤:	±1% or ±1pF, whichever is larger	Step 1 2 3 4	(Temperature) (°C)  (Low- category temp.):     (C0G:-55)  (Normal temp.): +20°C  (Up- category temp.)     (C0G: +125)  (Normal temp.): +20°C	30min 2~3min 30min			
		1 2 3 4	(Low- category temp.): (C0G:-55)  (Normal temp.): +20°C  (Up- category temp.) (C0G: +125)  (Normal temp.): +20°C	2~3min			
o visible d	damage.	3 4	(Up- category temp.) (C0G: +125) (Normal temp.): +20°C	30min			
		4	(C0G: +125) (Normal temp.) : +20°C				
				2~3min			
		Recov	ery time after test: 24±2h				
	Class I : ±7.5% or ±0.75pF, whichever is larger.						
Q :	≤2Not more than twice of initial value.						
IR I	Ri≥1000MΩ	Duration Recover	on: 500h ery conditions: Room temperature				
Appeara	nce: No visible damage.	Recov	Recovery Time: 24±2h				
7 C/C +	±2% or ±1pF, whichever is larger.						
Q N	Not more than twice of initial value.	Annlied	d Voltage:				
ום ו	Ri≥4000MΩ或 Ri•C <sub>R</sub> ≥40S whichever is smaller.	Rated 100V≤ 200V< Duratio	Voltage<100V: 2Ur Rated Voltage≤200V: 1.5 Ur <rated 1.3="" ur<br="" voltage≤500v:="">on: 1000h</rated>				
ppearand	ce: No visible damage.	Charge Recove	e/ Discharge Current: 50mA max. ery Conditions: Room Temperature				
7	IR Appeara  C/C =	IR Ri≥1000MΩ  Appearance: No visible damage.  C/C ±2% or ±1pF, whichever is larger.  Q Not more than twice of initial value.  Ri≥4000MΩ或 Ri•C <sub>R</sub> ≥40S	Ri≥1000MΩ  Appearance: No visible damage.  C/C ±2% or ±1pF, whichever is larger.  Q Not more than twice of initial value.  Applied Rated 100V≤ whichever is smaller.  Applied Rated 100V≤ 200V < 200V < 200V < 0.000	Humidity: 90~95%RH   Voltage: Rated Voltage   Duration: 500h   Recovery conditions: Room temperature   Recovery Time: 24±2h			



## ◆ Package



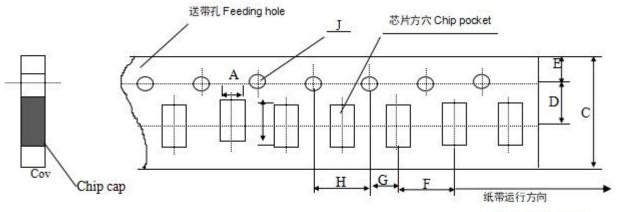
\* Dimensions of paper taping for 0201.0402 type



Code	W1	L1	D	С	В	P1	P2	P0	d	t
0201	0.37±	0.67±0.	8.00±	3.50±	1.75±	2.00±	2.00±	4.00±0	1.50	0.80
	0.10	10	0.10	0.05	0.10	0.05	0.05	.10	-0/+0.10	Below
0402	0.65±	1.15±	8.00±	3.50±	1.75±	2.00±	2.00±	4.00±0	1.50	0.80
	0.10	0.10	0.10	0.05	0.10	0.05	0.05	.10	-0/+0.10	Below



\* Dimensions of paper taping for 0603, 0805 types.

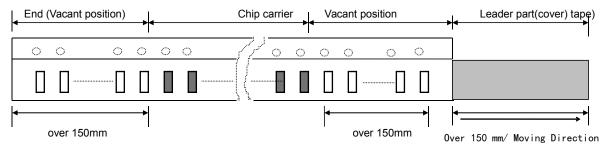


Tape running direction

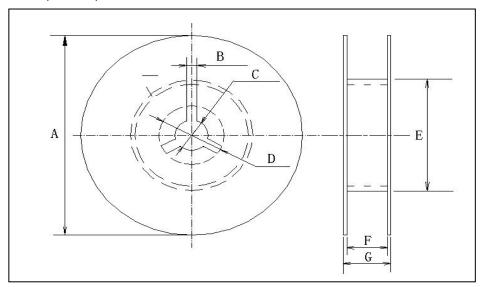
_									·	Unit: mm
Code paper size	A	В	C	D*	E	F	G*	Н	J	Т
0603	1.10	1.90	8.00	3.50	1.75	4.00	2.00	4.00	1.50	1.10
	± 0.10	± 0.10	± 0.10	± 0.05	± 0.10	± 0.10	± 0.10	± 0.10	-0/+0.10	Max
0805	1.45	2.30	8.0	3.50	1.75	4.00	2.00	4.00	1.50	1.10
	± 0.15	± 0.15	± 0.15	± 0.05	± 0.10	± 0.10	± 0.10	± 0.10	-0/+0.10	Max

Note: The place with " $\star$ " means where needs exactly dimensions.

\* Structure of leader part and end part of the carrier paper



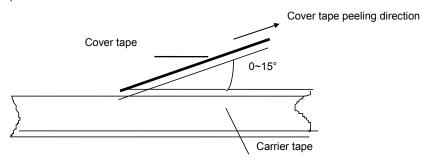
\* Reel dimensions (unit: mm)





Reel type	Α	В	С	D	Е	F	G
7'REEL	φ178±2.0	3.0	φ13±0.5	φ21±0.8	φ50 or more	10.0±1.5	12max

\* Taping specification: top tape peeling strength Paper Tapin



Standard: 0.1N < peeling strength < 0.7N

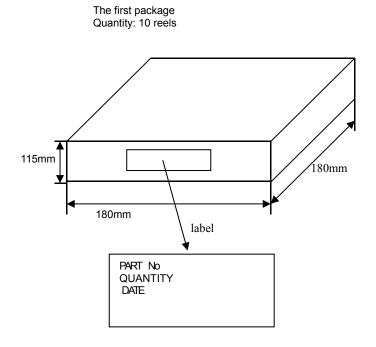
No paper dirty remains on the scotch when peeling, and sticks to top and bottom tape.

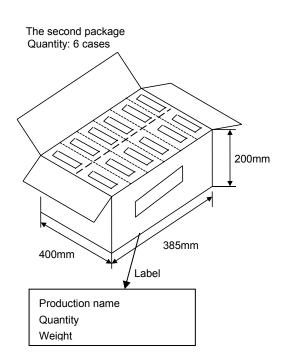
#### \* Packing Quantity

尺寸	( Package Style & Quantity) unit: pcs										
(SIZE)	(EPT)	(PT)	(ET)	(BC)	(BP)						
0201		15000		20000	5000						
0402		10000		20000	5000						
0603		4000		15000	5000						
0805		4000	3000	10000	5000						

Note: We can choose packing style and quantity can be according to the customer's requirement.

### \* Outer packing







#### Storage Methods

\* The guaranteed period for solderability is 12 months (Under deliver package condition).

\* Storage conditions: Temperature 5~40°C

Relative Humidity 20~70%

## **◆Precautions For Use**

The Multi-layer Ceramic Capacitors (MLCC) may fail in a short circuit modern in an open circuit mode when subjected to severe conditions of electrical environment and / or mechanical stress beyond the specified "rating" and specified "conditions" in the specification, which will result in burn out, flaming or glowing in the worst case. Following "precautions for "safety" and Application Notes shall be taken in your major consideration. If you have a question about the precautions for handling, please contact our engineering section or factory.

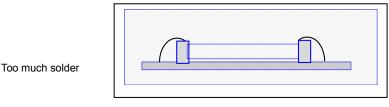
#### \* Soldering Profile

To avoid the crack problem by sudden temperature change, follow the temperature profile in the adjacent graph (refer to the graph in the enclosure page).

#### \* Manual Soldering

Manual soldering can pose a great risk of creating thermal cracks in capacitors. The hot soldering iron tip comes into direct contact with the end terminations, and operator's careless may cause the tip of the soldering iron to come into direct contact with the ceramic body of the capacitor. Therefore the soldering iron must be handled carefully, and pay much attention to the selection of the soldering iron tip and temperature contact of the tip.

#### \*Optimum Solder Amount for Reflow Soldering



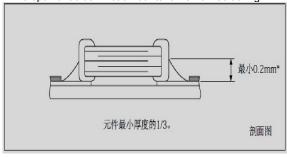
Cracks tend to occur due to large stress.

Not enough solder

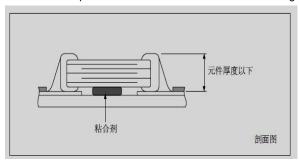
Weak holding force may cause badconnection between the capacitor and PCB.

#### \* Recommended Soldering amounts

The optimal solder fillet amounts for re-flow soldering

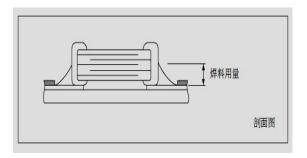


The optimal solder fillet amounts for wave soldering





The optimal solder fillet amounts for reworking by using soldering iron



### \* Recommended Soldering Method

Size	Temperature Characteristics	RatedVoltage	Capacitance	Soldering Method
0201	COG	1	1	R
0402	COG	/	1	R
0603	COG	1	1	R/W
0805 C0G		1	/	R/W

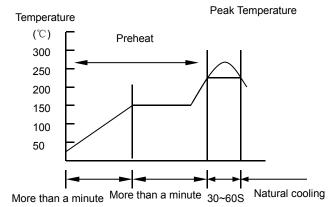
Soldering method: Reflow Solering Wave Soldering

### ◆ The temperature profile for soldering

#### \* (Re-flow soldering)

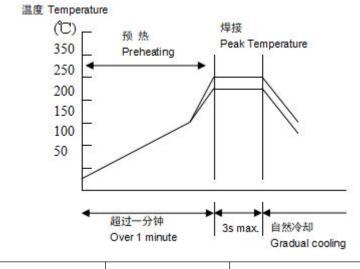
	Pb-Sn soldering	Lead-free soldering
Peak temperature	230℃~250℃	240℃~260℃

While in preheating,please keep the temperature difference between soldering temperature and surface temperature of chips as:  $T \le 150^{\circ}C$ .





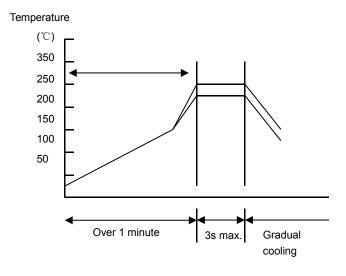
#### \* (Wave soldering)



Pb-Sn solderin		Lead-free soldering	
Peak temperature	230℃~260℃	240℃~270℃	

While in preheating, please keep the temperature difference between soldering temperature and surface temperature of chips as:  $T \le 150$  °C.

### \* Hand soldering



#### Conditions:

Preheating	Temperature of soldering iron head	Power of soldering iron	Diameter of soldering iron head	Soldering time	Solder paste amount	Restricted conditions
∆≤130°C	Highest temperature:35	20W at the highest	1mm recommended	3s at the longest	≤1/2 chip thickness	Please avoid the derect contact between soldering iron head and ceramic components

<sup>\*</sup>The contents of the latest version shall prevail